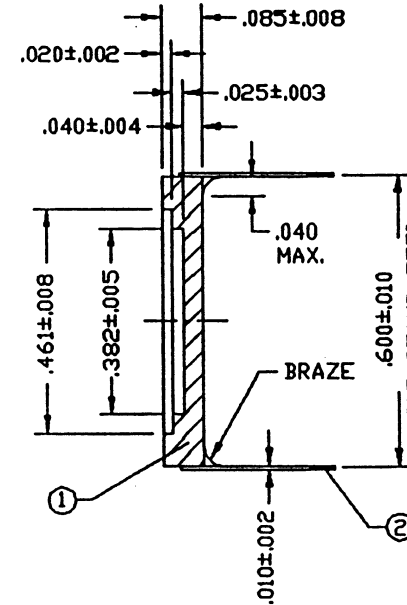
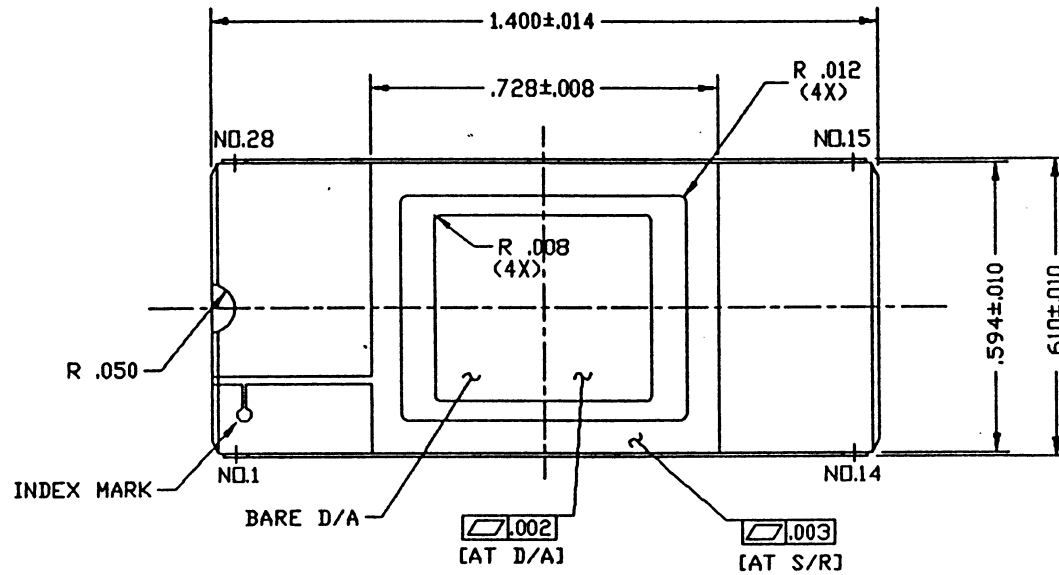
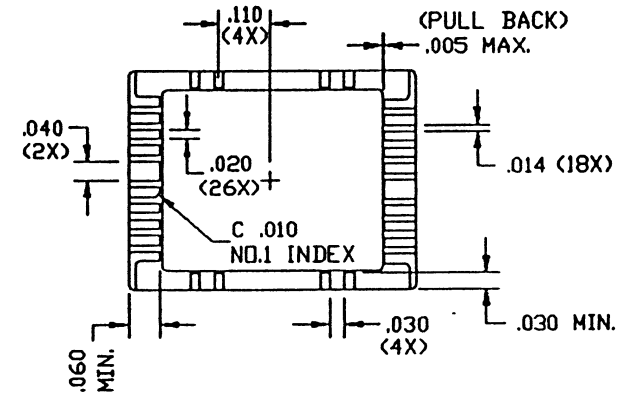
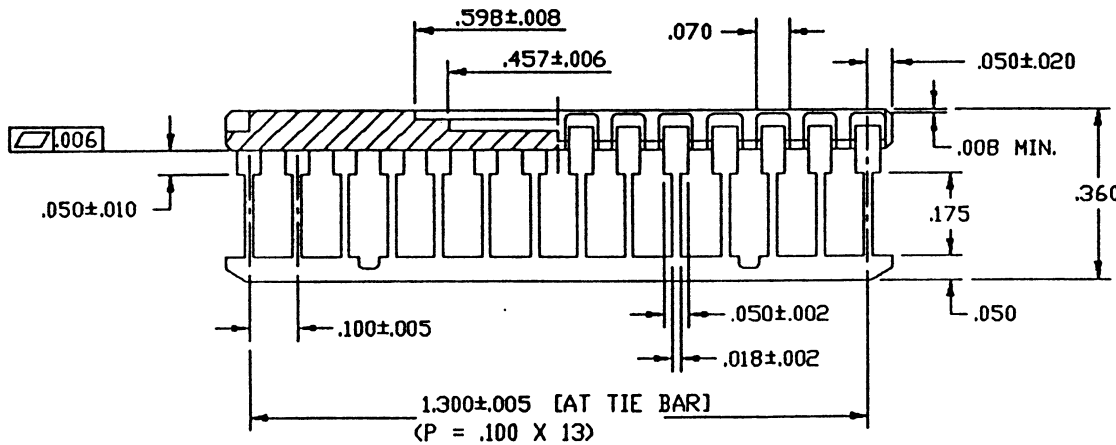


REVISIONS				DATE	APPROVED
ZONE	REV	ECN	DESCRIPTION		
	MM	768	NEW RELEASE	07/22/94	



DOCUMENT CONTROL  
 MAR 15 1999  
 CONTROLLED COPY



NOTES:

- GOLD PLATE  $80 \mu$  INCHES MIN. OVER  $80 \mu$  INCHES MIN. NICKEL.
- NO LEAD TO BE ELECTRICALLY CONNECTED TO DIE ATTACH PAD. SEAL RING ISOLATED.
- LEAD RESISTANCE:  $800 \text{ m}\Omega$  MAX.

UNLESS OTHERWISE SPECIFIED		DESIGNED BY	DATE
ALL DIMENSIONS ARE IN INCHES		DRW	DATE
STANDARD TOLERANCES UNLESS OTHERWISE SPECIFIED		HTN	07/22/94
DRAWN	DATE	CHK BY	DATE
SIZE	DATE	APPROVED BY	DATE
SCALE	DATE	APPROVED BY	DATE
MATERIAL	DATE	APPROVED BY	DATE
FINISH	DATE	APPROVED BY	DATE
TITLE		SIZE	REV
28.6 SIDEBRAZE 382 X 457		C	MM
PART NO.		BSB2861	
DWG NO.		51-20256	
SHEET		1 OF 1	

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THIS DRAWING

CSB02829